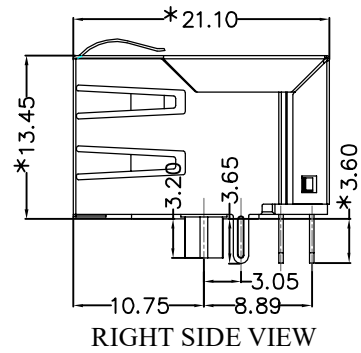
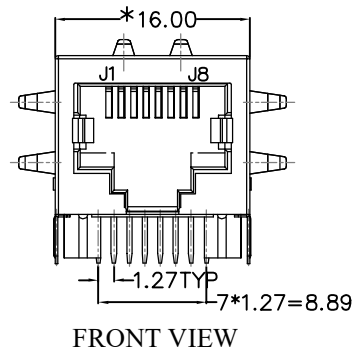


REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	

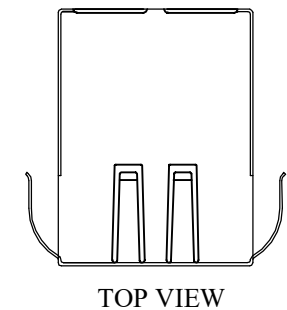
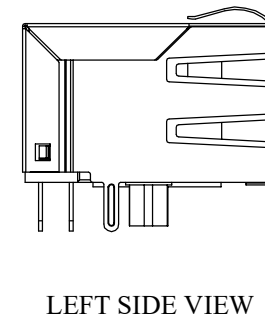
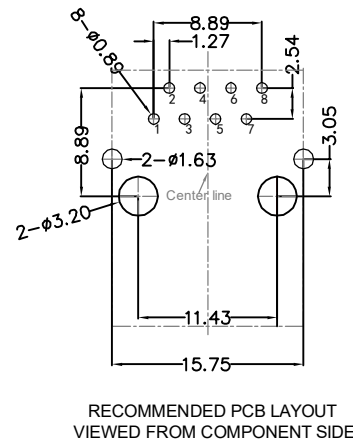
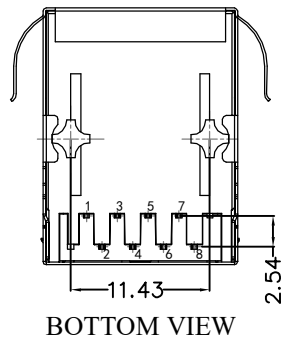
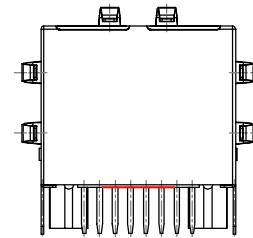


MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
 6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

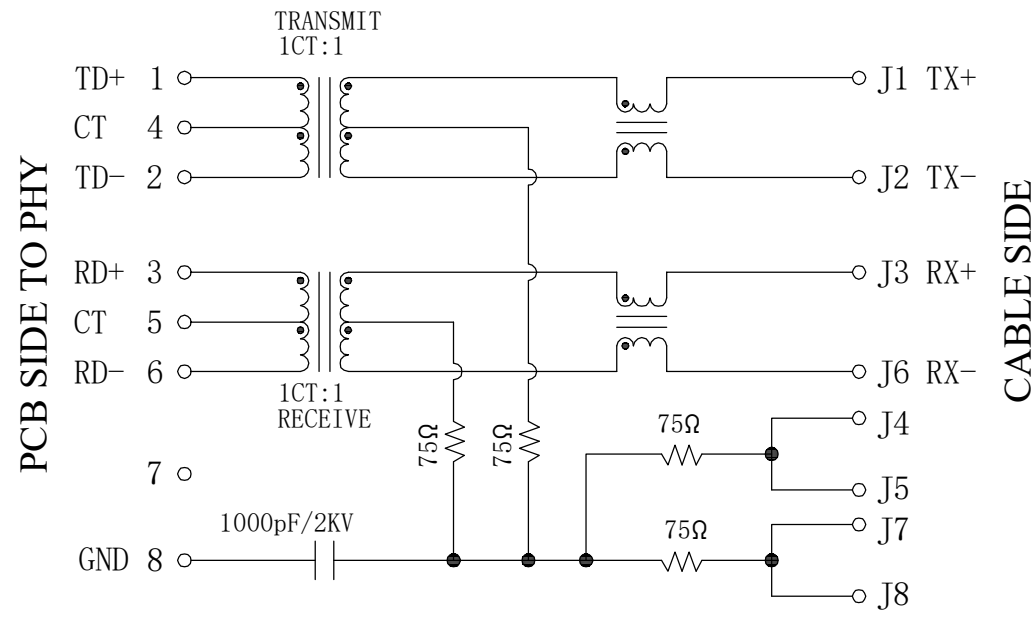
DURABILITY: 750 CYCLES MIN.
 MATING FORCE: 23N MAX.
 OPERATING TEMPERATURE: -40°C~+85°C.
 STORAGE TEMPERATURE: -40°C~+85°C.
 ALL CRITICAL DIMENSIONS WITH "*"



PART NO.	111B002HWA1D	DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY

TITLE: TAB-DOWN 1X1 100BASE	REV. A0	.X°±2°	.XX±0.25	SCALE 1:1	UNIT mm	NO	DESCRIPTION
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REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	



Electrical:

1. Turn ratio: 1~2: J1~J2=1CT:1CT(±2%).
3~6: J3~J6=1CT:1CT(±2%).
2. OCL: 350uH Min. at 100KHz 100mV 8mA DC.
3. Insertion Loss: -1.0 dB Max 1~100MHz.
4. Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz.
-12dB Min 30~60MHz.
-10dB Min 60~80MHz.
5. Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
6. CMR: -30dB Min 1~100MHz;
7. Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

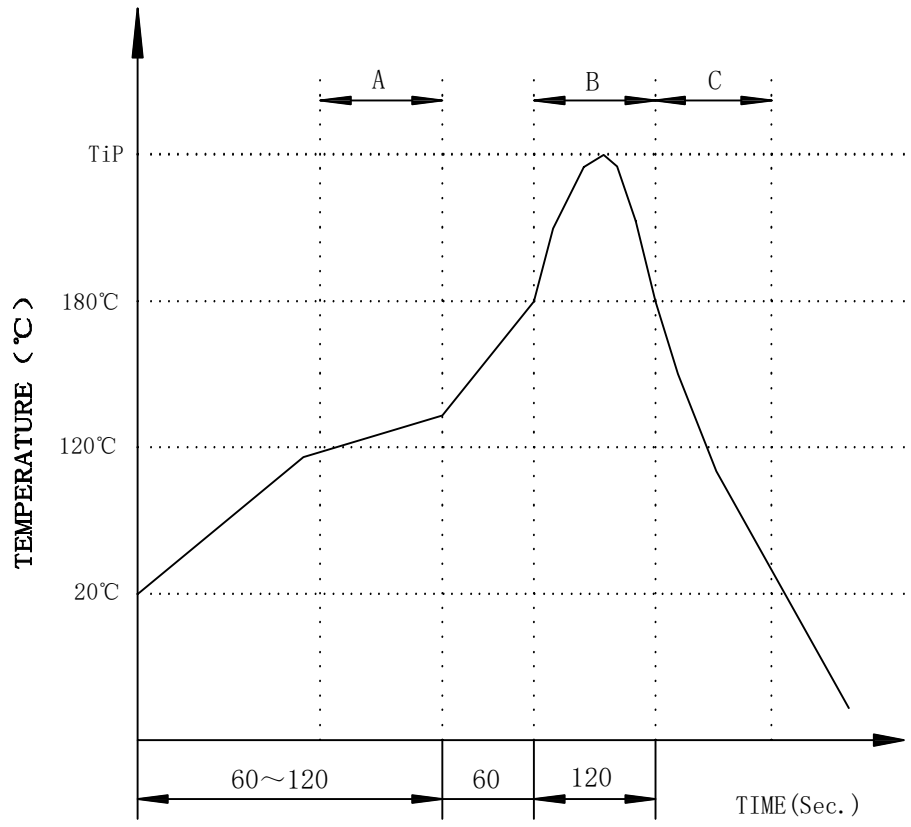


PART NO.	111B002HWA1D	DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY
TITLE:	TAB-DOWN 1X1 100BASE	SCALE	1:1
REV.	A0	UNIT	mm
	.X°±2°	NO	
	.XX±0.25		

TITLE:	REV.	TOLERANCE	SCALE	UNIT	mm	NO	DESCRIPTION
TAB-DOWN 1X1 100BASE	A0	.X°±2°	1:1	mm			

REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.	2020.07.06	

PROFILE OF WAVE SOLDER



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

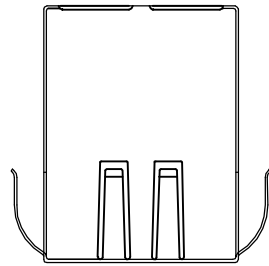


PART NO.	111B002HWA1D	DRAWN	MARK
DRAWING NO.		CHECK	JOHN
TOLERANCE	X.±0.35 .X±0.30	APPROVE	MELODY
TITLE: TAB-DOWN 1X1 100BASE	REV. A0	.X°±2°	.XX±0.25

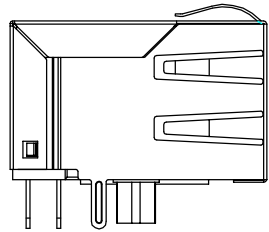
SCALE	1:1	UNIT	mm	NO	DESCRIPTION

REACH & RoHS
COMPLIANT

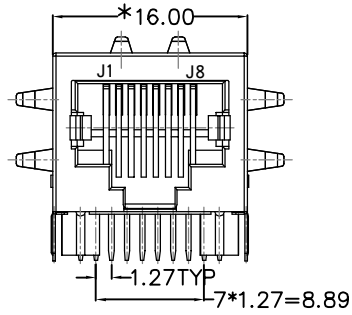
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.10.18



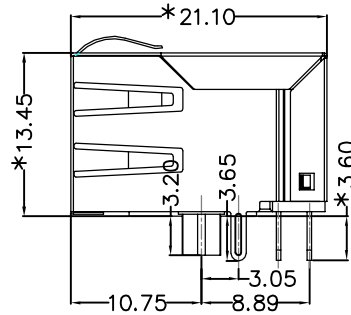
TOP VIEW



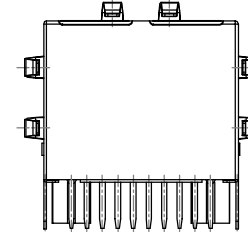
LEFT SIDE VIEW



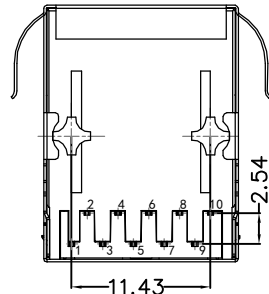
FRONT VIEW



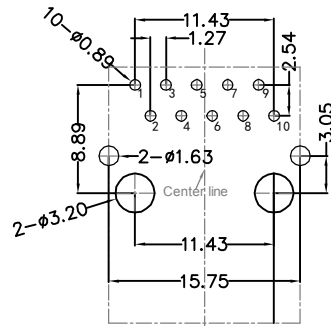
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
 6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

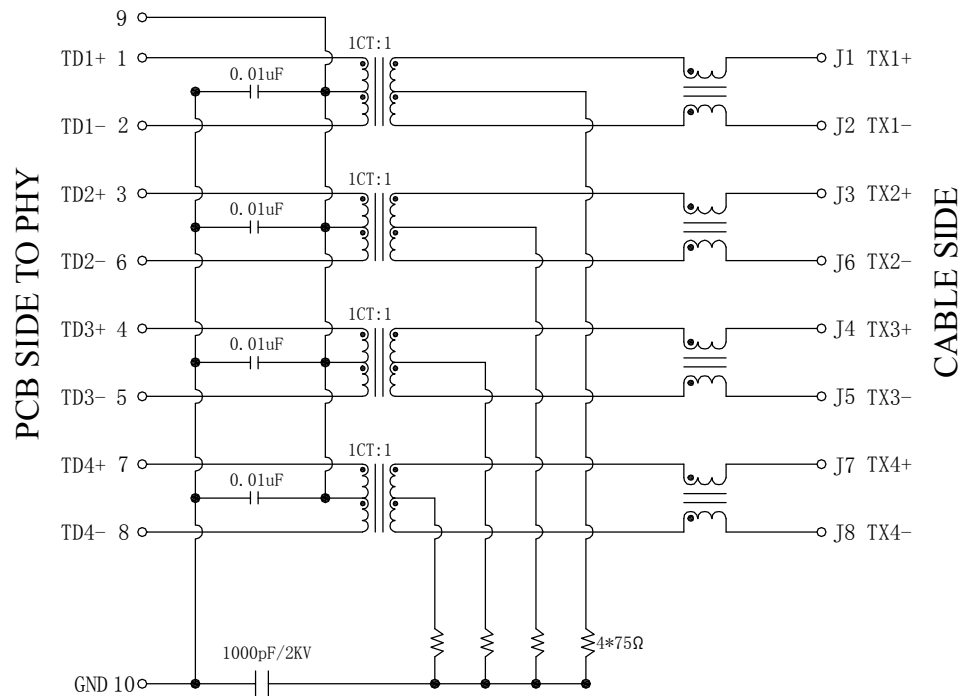
DURABILITY: 750 CYCLES MIN.
 MATING FORCE : 30N MAX.
 OPERATING TEMPERATURE: -40°C~+85°C.
 STORAGE TEMPERATURE: -40°C~+85°C.
 ALL CRITICAL DIMENSIONS WITH "*"

CELION SAS

TITLE: TAB-DOWN 1X1 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: 111Q068HWA1D	SACLE 1:1	REV A0	x±0.35 .x±0.30	x°±3.0° .x°±2.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/3		.xx±0.25 .xxx±0.10	.xx°±1.5° .xxx°±1.0°	DESIGND BY: MQ.Qu

REACH & RoHS
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.10.18



Electrical:

- Turn ratio: 1~2: J1~J2 = 1CT:1CT(±2%).
3~6: J3~J6 = 1CT:1CT(±2%).
4~5: J4~J5 = 1CT:1CT(±2%).
7~8: J7~J8 = 1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz.
-12dB Min 30~60MHz.
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -35dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

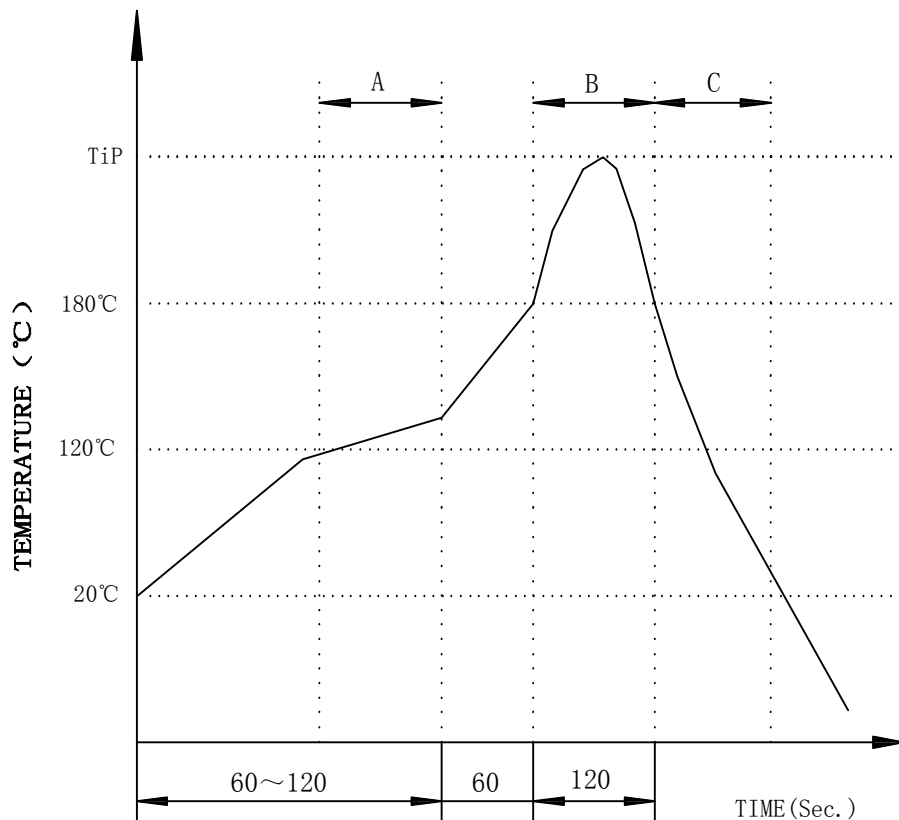
CELION SAS

TITLE: TAB-DOWN 1X1 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: 111Q068HWA1D	SACLE 1:1	REV A0	x±0.35 .x±0.30	x°±3.0° .x°±2.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 2/3		.xx±0.25 .xxx±0.10	.xx°±1.5° .xxx°±1.0°	DESIGND BY: MQ.Qu

REACH & RoHS
COMPLIANT

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.10.18



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

CELION SAS

TITLE: TAB-DOWN 1X1 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: 111Q068HWA1D	SACLE 1:1	REV A0	x±0.35 .x±0.30	x°±3.0° .x°±2.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 3/3		.xx±0.25 .xxx±0.10	.xx°±1.5° .xxx°±1.0°	DESIGND BY: MQ.Qu